



Amendments to the Specification

Please replace paragraph [0008] of the specification with the following amended paragraph [0008]:

[0008] In order to achieve the above object, the present invention provides a method for manufacturing a conductive pattern forming body comprising: a ~~pattern forming body substrate preparing~~ process of preparing a pattern forming body substrate comprising a base material, and a photocatalyst containing layer formed on the base material comprising a photocatalyst and a binder whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced; a ~~wettability pattern forming~~ process of forming a wettability pattern comprising a liquid repellent area and a lyophilic area on the photocatalyst containing layer by irradiating the photocatalyst containing layer in a pattern with energy; a metal colloid coating process of adhering a metal colloid only to the lyophilic area of the surface of the photocatalyst containing layer on which the wettability pattern is formed, by coating the metal colloid; and a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered to the lyophilic area of the wettability pattern.

Please replace paragraph [0016] of the specification with the following amended paragraph [0016]:

[0016] And further, the coating of the metal colloid in the metal colloid coating process may be a ~~nozzled is charging~~ nozzle discharging method. Among the above, the nozzle discharging method is preferably an ink jet method.

Please replace paragraph [0017] of the specification with the following amended paragraph [0017]:

[0017] In the above invention, the photocatalyst is preferably titanium dioxide oxide (TiO₂). Since titanium dioxide has high bandgap energy, it is effective as a photocatalyst, and also, it is chemically stable without any toxicity, and is easily available.

Please replace paragraph [0018] of the specification with the following amended paragraph [0018]:

[0018] The present invention provides a method for manufacturing a conductive pattern forming body comprising: ~~a pattern-forming body substrate~~ ~~preparing~~ process of preparing a pattern forming body substrate comprising a base material, a photocatalyst treatment layer formed on the base material containing at least a photocatalyst, and a wettability variable layer formed on the photocatalyst treatment layer which is a layer whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced; ~~a wettability-pattern-forming~~ process of forming a wettability pattern comprising a liquid repellent area and a lyophilic area on the wettability variable layer by irradiating the wettability variable layer in a pattern with energy; a metal colloid coating process of adhering a metal colloid only to the lyophilic area of the surface of the wettability variable layer on which the wettability pattern is formed, by coating the metal colloid; and ~~a conductive pattern-forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered to the lyophilic area of the wettability pattern.

Please replace paragraph [0026] of the specification with the following amended paragraph [0026]:

[0026] In the above invention, the photocatalyst is preferably titanium dioxide oxide (TiO_2). Since titanium dioxide has high bandgap energy, it is effective as a photocatalyst, and also, it is chemically stable without any toxicity, and is easily available.

Please replace paragraph [0027] of the specification with the following amended paragraph [0027]:

[0027] The present invention provides a method for manufacturing a conductive pattern forming body comprising: ~~a pattern-forming body substrate~~ ~~preparing~~ process of preparing a pattern forming body substrate comprising a base material, a photocatalyst treatment layer formed on the base material containing at least a photocatalyst, and a decomposition removal layer formed on the

photocatalyst treatment layer which is decomposed and removed by an action of the photocatalyst by energy irradiation; a ~~decomposition removal pattern forming~~ process of forming a decomposition removal pattern on the decomposition removal layer by irradiating the decomposition removal layer in a pattern with energy; a metal colloid coating process of adhering a metal colloid in a pattern to the surface of the decomposition removal layer on which the decomposition removal pattern is formed, by coating the metal colloid; and a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered in a pattern.

Please replace paragraph [0035] of the specification with the following amended paragraph [0035]:

[0035] In the above invention, the photocatalyst is preferably titanium dioxide oxide (TiO_2). Since titanium dioxide has high bandgap energy, it is effective as a photocatalyst, and also, it is chemically stable without any toxicity, and is easily available.

Please replace paragraph [0036] of the specification with the following amended paragraph [0036]:

[0036] Also, the present invention provides a method for manufacturing a conductive pattern forming body comprising: a property variable pattern forming process of placing a photocatalyst treatment layer side substrate comprising a base member and a photocatalyst treatment layer containing a photocatalyst, and a pattern forming body substrate comprising a property variable layer whose property is changed by an action of a photocatalyst in the photocatalyst treatment layer so that the photocatalyst treatment layer and the property variable layer are placed with a gap of 200 μm or less, and then, irradiating with energy from predetermined direction to form a property variable pattern, whose property is changed, on a surface of the property variable layer; a metal colloid coating process of adhering a metal colloid in a pattern to the surface of the pattern forming body substrate on which the property variable pattern is formed by coating the metal colloid; and a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered in a pattern to the property variable pattern.

Please replace paragraph [0039] of the specification with the following amended paragraph [0039]:

[0039] Also, in the above invention, it is preferable that the photocatalyst treatment layer side substrate prepared in the photocatalyst treatment layer side substrate ~~preparing~~ preparing process comprises the base member, the photocatalyst treatment layer formed on the base member, and a photocatalyst treatment layer side light shielding part formed in a pattern; and the energy irradiation in the property variable pattern forming process is carried out from the photocatalyst treatment layer side substrate.

Please replace paragraph [0045] of the specification with the following amended paragraph [0045]:

[0045] In the above invention, the photocatalyst is preferably titanium dioxide oxide (TiO_2). Since titanium dioxide has high bandgap energy, it is effective as a photocatalyst, and also, it is chemically stable without any toxicity, and is easily available.

Please replace paragraph [0063] of the specification with the following amended paragraph [0063]:

[0063] Also, the present invention provides a conductive pattern forming body comprising: a base material; a photocatalyst treatment layer contains at least a photocatalyst, on the base material; a wettability variable layer whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced, on the photocatalyst treatment layer; and a metal composition formed on the wettability variable layer by solidifying a metal colloid in a pattern. According to the present invention, by providing the wettability variable layer, the metal colloid can be adhered ~~easily~~ easily in a pattern in high precision by utilizing a difference in wettability. Also, since the photocatalyst treatment layer and the conductive pattern are not directly contacted, the possibility of the conductive pattern being affected with time by the photocatalyst is low, which makes it possible to produce a high quality conductive pattern forming body.

Please replace paragraph [0065] of the specification with the following amended paragraph [0065]:

[0065] According to the present invention, by providing the wettability variable layer, the metal colloid can be adhered ~~easily~~ easily in a pattern in high precision by utilizing a difference in wettability. Also, since the photocatalyst treatment layer and the conductive pattern are not directly contacted, the possibility of the conductive pattern being affected with time by the photocatalyst is low, which makes it possible to produce a high quality conductive pattern forming body. Further, since the wettability variable layer is formed in a pattern and the relatively insulating photocatalyst treatment layer is bared in a part other than the conductive pattern, it is possible to form a conductive pattern forming body even if the wettability variable layer is electrically conductive.

Please replace paragraph [0067] of the specification with the following amended paragraph [0067]:

[0067] According to the present invention, by providing the wettability variable layer, the metal colloid can be adhered ~~easily~~ easily in a pattern in high precision by utilizing a difference in wettability. Also, since the photocatalyst containing layer is formed in a patten, and the wettability variable layer and the conductive pattern are formed thereon, the relatively insulating base material is bared in a part other than the conductive pattern so that a conductive pattern forming body can be formed even if the wettability variable layer and the photocatalyst treatment layer are electrically conductive.

Please replace paragraph [0074] of the specification with the following amended paragraph [0074]:

[0074] Also, the present invention provides a conductive pattern forming body comprising: ~~a base~~ a base material; a decomposition removal layer on the base material which is decomposed and removed by an action of a photocatalyst; and a metal composition formed on the base material which is bared by the decomposition

and removal of the decomposition removal layer, by solidifying a metal colloid in a pattern.

Please replace paragraph [0101] of the specification with the following amended paragraph [0101]:

[0101] a ~~pattern forming body substrate preparing~~ process of preparing a pattern forming body substrate comprising a base material, and a photocatalyst containing layer formed on the base material comprising a photocatalyst and a binder whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced;

Please replace paragraph [0102] of the specification with the following amended paragraph [0102]:

[0102] a ~~wettability pattern forming~~ process of forming a wettability pattern comprising a liquid repellent area and a lyophilic area on the photocatalyst containing layer by irradiating the photocatalyst containing layer in a pattern with energy;

Please replace paragraph [0104] of the specification with the following amended paragraph [0104]:

[0104] a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered to the lyophilic area of the wettability pattern.

Please replace paragraph [0197] of the specification with the following amended paragraph [0197]:

[0197] As mentioned above, when the organopolysiloxane is used as the binder, the photocatalyst containing layer may be formed by dispersing the photocatalyst and the organopolysiloxane as the binder together with other additives, as needed, into a solvent to prepare a coating ~~solutie~~ solution, and by coating the

coating solution to a base material. As the solvent to be used, an alcohol type organic solvent such as ethanol or isopropanol is preferable. The coating solution may be coated by a known coating method such as a spin coating, spray coating, dip coating, roll coating or beads coating. In a case where an ultraviolet curing type component is contained as the binder, the photocatalyst containing layer may be formed by irradiating ultraviolet rays to carry out curing treatment.

Please replace paragraph [0208] of the specification with the following amended paragraph [0208]:

[0208] For example, a thin film of a metal such as chromium may be formed into a thickness of about 1000 to 2000 Å by a sputtering method or vacuum deposition method, and patterned to form the light shielding part. As this patterning method, a usual [[sual]] patterning method such as sputtering may be used.

Please replace paragraph [0239] of the specification with the following amended paragraph [0239]:

[0239] ~~a pattern-forming body-substrate-preparing~~ process of preparing a pattern forming body substrate comprising a base material, a photocatalyst treatment layer formed on the base material containing at least a photocatalyst, and a wettability variable layer formed on the photocatalyst treatment layer which is a layer whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced;

Please replace paragraph [0240] of the specification with the following amended paragraph [0240]:

[0240] ~~a wettability pattern-forming~~ process of forming wettability pattern comprising a liquid repellent area and a lyophilic area on the wettability variable layer by irradiating the wettability variable layer in a pattern with energy;

Please replace paragraph [0242] of the specification with the following amended paragraph [0242]:

[0242] a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered to the lyophilic area of the wettability pattern.

Please replace paragraph [0275] of the specification with the following amended paragraph [0275]:

[0275] a ~~pattern forming body substrate preparing~~ process of preparing pattern forming body substrate comprising a base material, a photocatalyst treatment layer formed on the base material containing at least a photocatalyst, and a decomposition removal layer formed on the photocatalyst treatment layer which is decomposed and removed by an action of the photocatalyst by energy irradiation;

Please replace paragraph [0276] of the specification with the following amended paragraph [0276]:

[0276] a decomposition removal pattern forming process of forming a decomposition removal pattern on the decomposition removal layer by irradiating the decomposition removal layer in a pattern with energy;

Please replace paragraph [0278] of the specification with the following amended paragraph [0278]:

[0278] a ~~conductive pattern forming~~ process of forming a conductive pattern by solidifying the metal colloid adhered in a pattern.